

Product Summary

BV _{DSS}	R _{DS(ON)} Max	I _D T _A = +25°C
50V	2Ω @ V _{GS} = 5V	350mA
	2.5Ω @ V _{GS} = 2.5V	330mA
	4Ω @ V _{GS} = 1.8V	270mA

Features and Benefits


- Low On-Resistance
- Very Low Gate Threshold Voltage (1.0V max)
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- **ESD Protected**
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **An automotive-compliant part is available under separate datasheet ([DMN52D0UDWQ](#))**

Description and Applications

This MOSFET is designed to minimize the on-state resistance (R_{DS(ON)}) yet maintain superior switching performance, making it ideal for high-efficiency power-management applications.

- Load switches
- Level switches

Mechanical Data

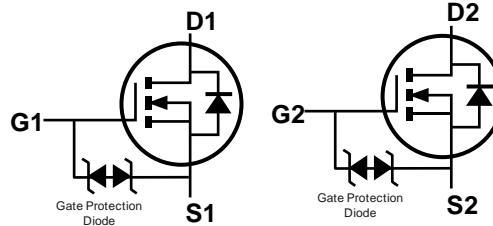
- Package: SOT363
- Package Material: Molded Plastic. "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish Annealed over Alloy 42 Leadframe. Solderable per MIL-STD-202, Method 208 
- Terminal Connections: See Diagram
- Weight: 0.006 grams (Approximate)



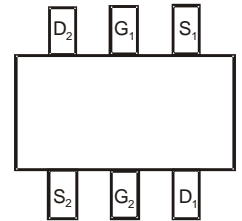
SOT363



Top View



Equivalent Circuit



Top View
Pinout

Ordering Information (Note 4)

Part Number	Package	Packing	
		Qty.	Carrier
DMN52D0UDW-7	SOT363	3,000	Reel
DMN52D0UDW-13	SOT363	10,000	Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
 2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

Marking Information



5DK = Product Type Marking Code
YM = Date Code Marking
Y = Year (ex: L = 2024)
M = Month (ex: 9 = September)

Date Code Key

Year	2023	2024	2025	2026	2027	2028	2029	2030	2031	2032	2033	2034
Code	K	L	M	N	P	R	S	T	U	V	W	X
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V _{DSS}	50	V
Gate-Source Voltage			V _{GSS}	±12	V
Continuous Drain Current (Note 6) V _{GS} = 5V	Steady State	T _A = +25°C T _A = +70°C	I _D	350 280	mA
Maximum Continuous Body Diode Forward Current (Note 6)			I _S	350	mA
Pulsed Drain Current (10μs Pulse, Duty Cycle = 1%)			I _{DM}	1.2	A

Thermal Characteristics

Characteristic			Symbol	Value	Unit
Total Power Dissipation (Note 5)			P _D	0.3	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State		R _{θJA}	373	°C/W
Total Power Dissipation (Note 6)			P _D	0.5	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State		R _{θJA}	241	°C/W
Operating and Storage Temperature Range			T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV _{DSS}	50	—	—	V	V _{GS} = 0V, I _D = 250μA
Zero Gate Voltage Drain Current	I _{DSS}	—	—	1	μA	V _{DS} = 50V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}	—	—	±10	μA	V _{GS} = ±12V, V _{DS} = 0V
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	V _{GS(TH)}	0.49	—	1.0	V	V _{DS} = V _{GS} , I _D = 250μA
Static Drain-Source On-Resistance	R _{DS(ON)}	—	1.6	4.0	Ω	V _{GS} = 1.8V, I _D = 50mA
		—	1.2	2.5		V _{GS} = 2.5V, I _D = 50mA
		—	1.0	2.0		V _{GS} = 5.0V, I _D = 50mA
Diode Forward Voltage	V _{SD}	—	0.6	1.2	V	V _{GS} = 0V, I _D = 50mA
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C _{iss}	—	42.3	—	pF	V _{DS} = 25V, V _{GS} = 0V f = 1.0MHz
Output Capacitance	C _{oss}	—	5.7	—	pF	
Reverse Transfer Capacitance	C _{rss}	—	4.5	—	pF	
Gate Resistance	R _g	—	53	—	Ω	V _{DS} = 0V, V _{GS} = 0V, f = 1MHz
Total Gate Charge (V _{GS} = 4.5V)	Q _g	—	0.7	—	nC	V _{DS} = 25V, I _D = 50mA
Total Gate Charge (V _{GS} = 10V)	Q _g	—	1.5	—	nC	
Gate-Source Charge	Q _{gs}	—	0.1	—	nC	
Gate-Drain Charge	Q _{gd}	—	0.2	—	nC	
Turn-On Delay Time	t _{D(ON)}	—	1.1	—	ns	V _{DS} = 25V, V _{GS} = 10V, R _G = 50Ω, I _D = 50mA
Turn-On Rise Time	t _R	—	8.3	—	ns	
Turn-Off Delay Time	t _{D(OFF)}	—	31	—	ns	
Turn-Off Fall Time	t _F	—	41	—	ns	

- Notes:
- Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
 - Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate.
 - Short duration pulse test used to minimize self-heating effect.
 - Guaranteed by design. Not subject to product testing.

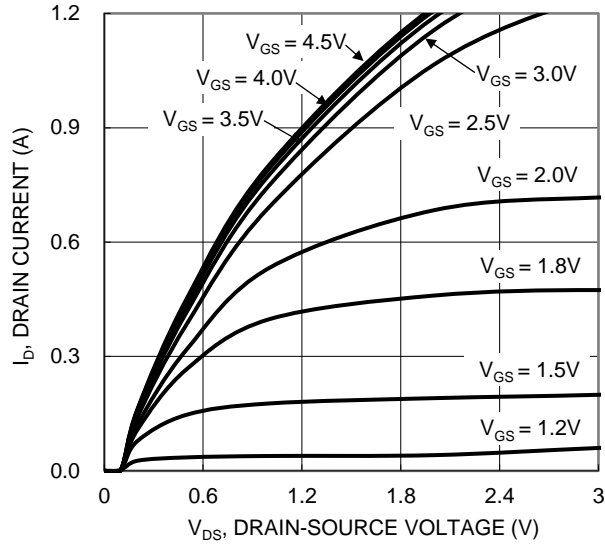


Figure 1. Typical Output Characteristic

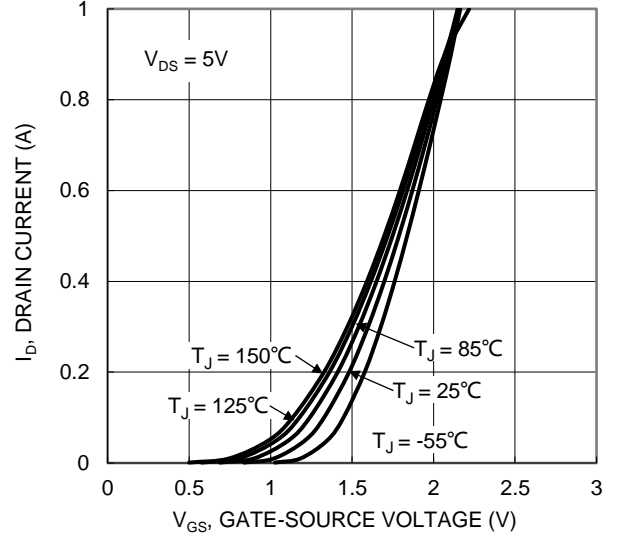


Figure 2. Typical Transfer Characteristic

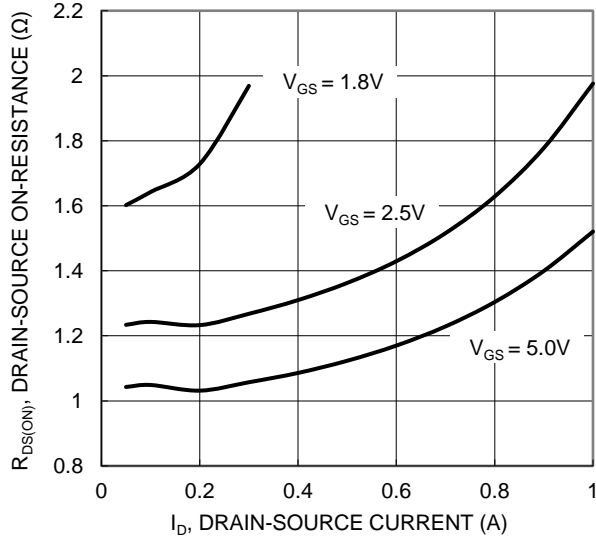


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

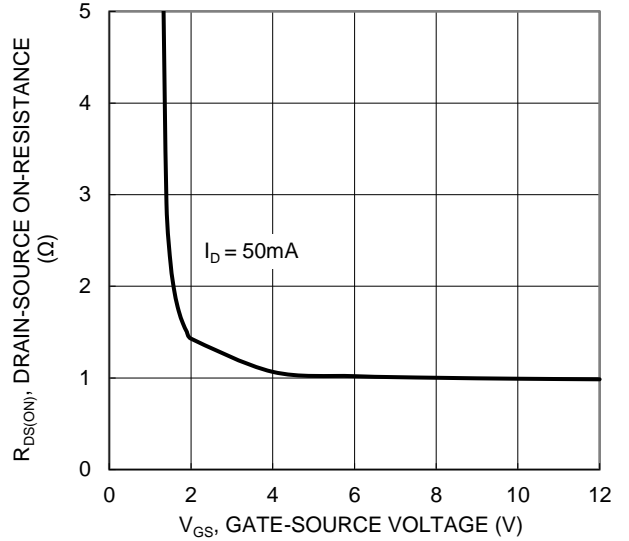


Figure 4. Typical Transfer Characteristic

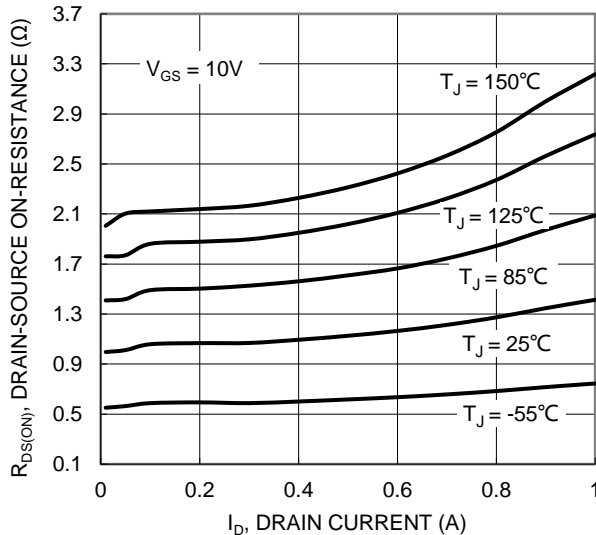


Figure 5. Typical On-Resistance vs. Drain Current and Temperature

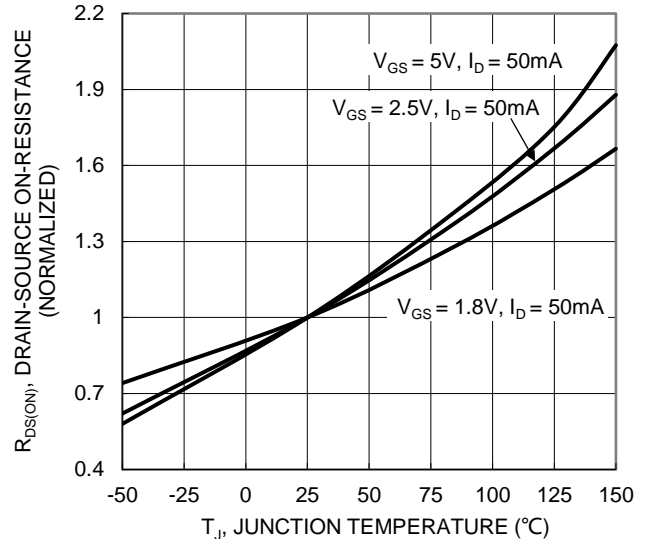


Figure 6. On-Resistance Variation with Temperature

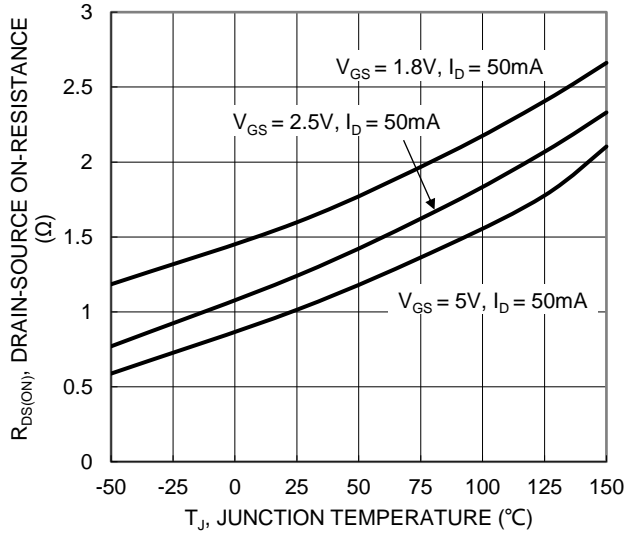


Figure 7. On-Resistance Variation with Temperature

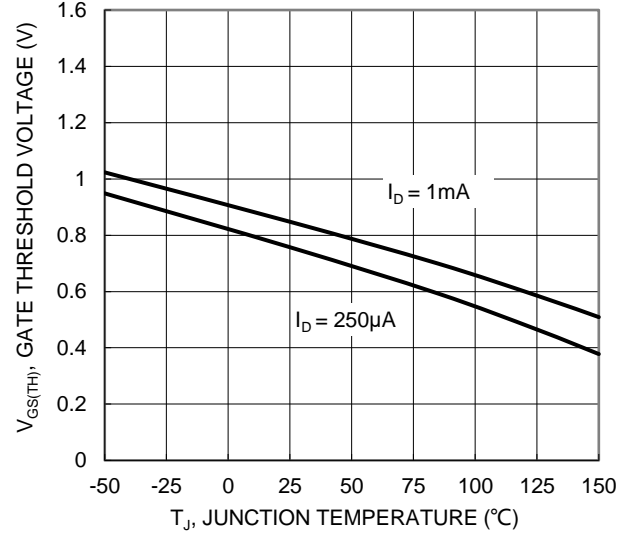


Figure 8. Gate Threshold Variation vs. Junction Temperature

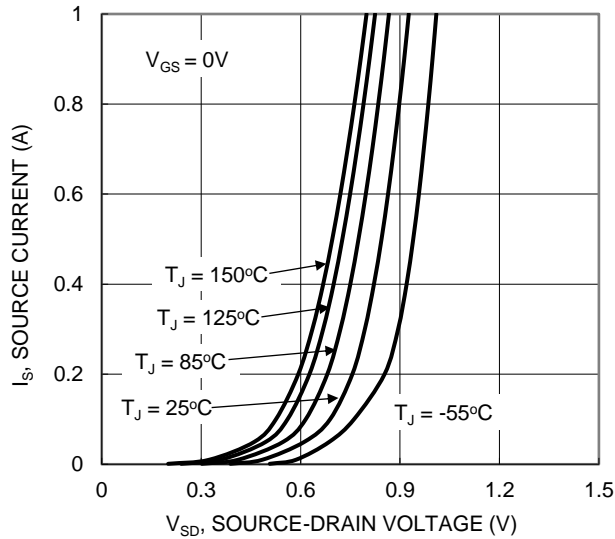


Figure 9. Diode Forward Voltage vs. Current

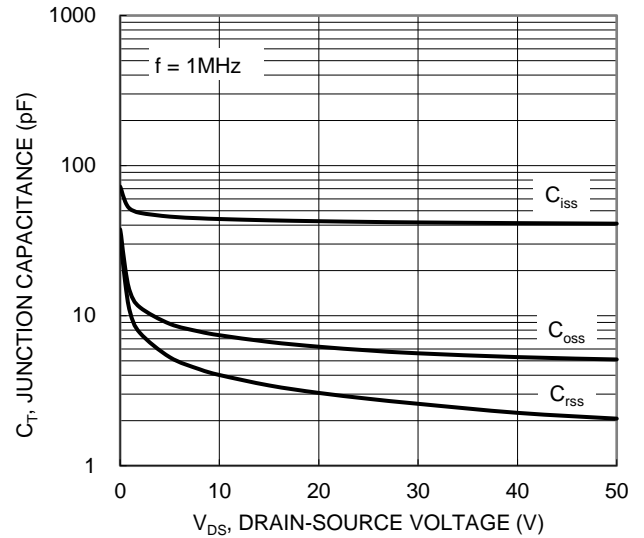


Figure 10. Typical Junction Capacitance

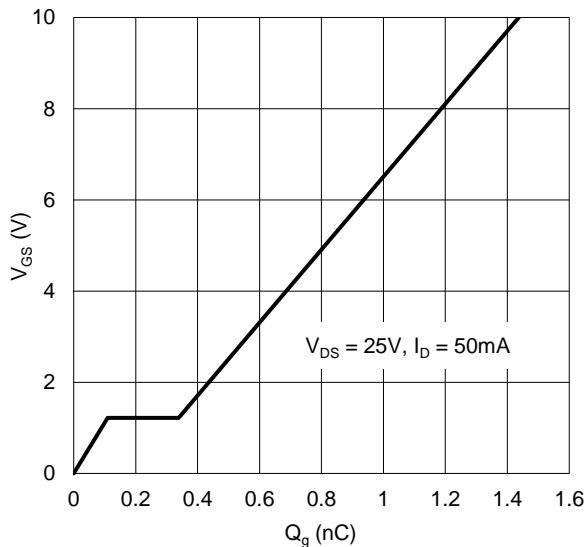


Figure 11. Gate Charge

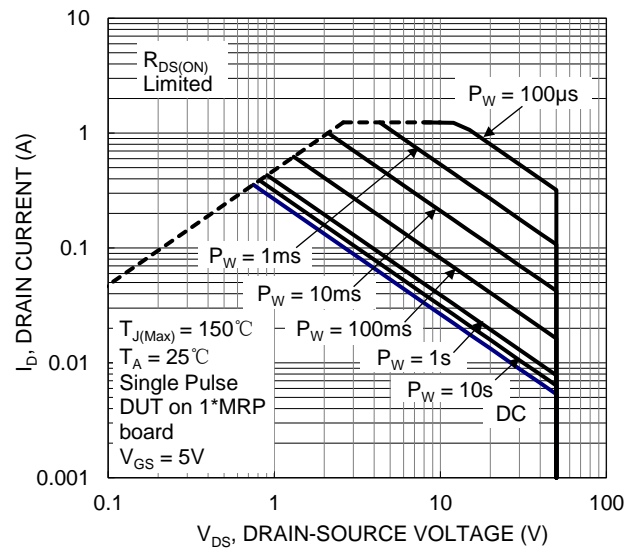


Figure 12. SOA, Safe Operation Area

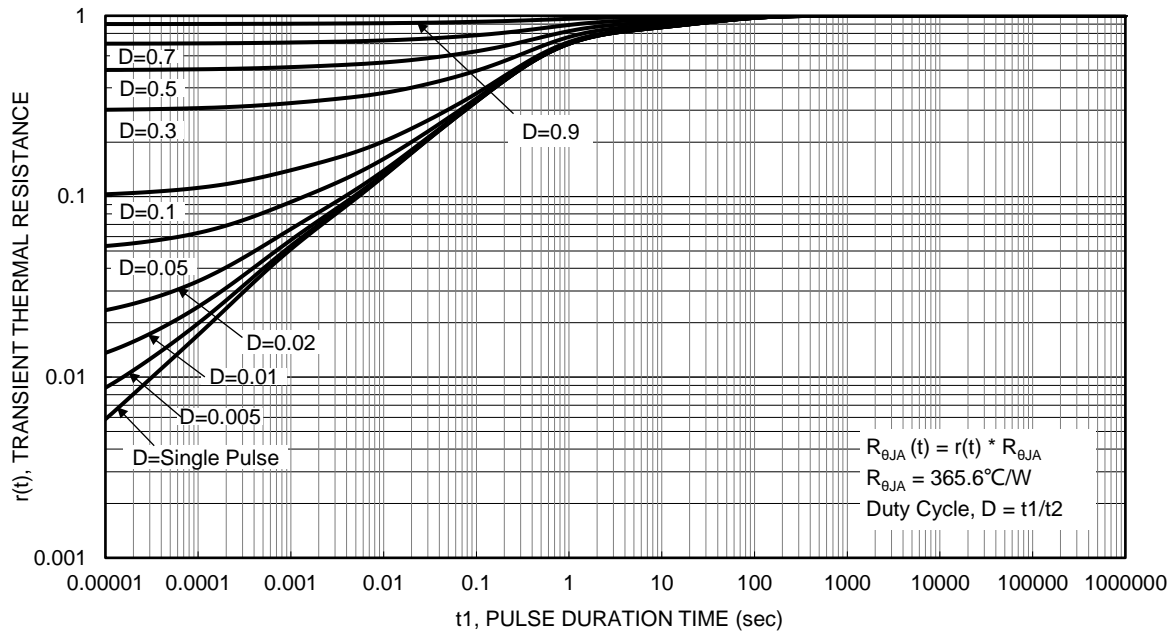
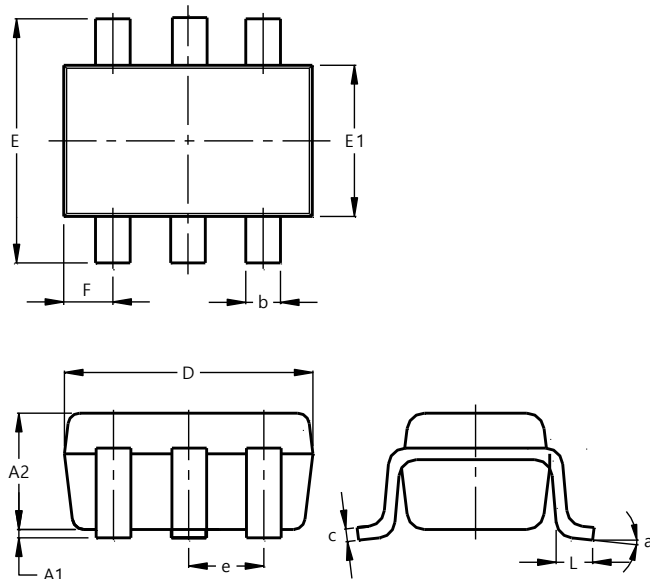


Figure 13. Transient Thermal Resistance

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOT363

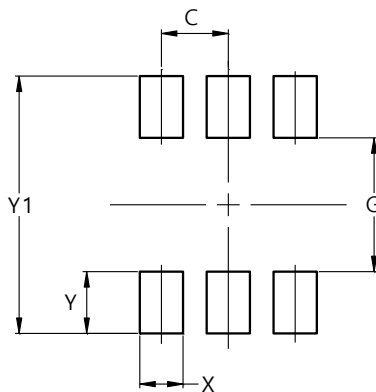


SOT363			
Dim	Min	Max	Typ
A1	0.00	0.10	0.05
A2	0.90	1.00	0.95
b	0.10	0.30	0.25
c	0.10	0.22	0.11
D	1.80	2.20	2.15
E	2.00	2.20	2.10
E1	1.15	1.35	1.30
e	0.650 BSC		
F	0.40	0.45	0.425
L	0.25	0.40	0.30
a	0°	8°	--
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOT363



Dimensions	Value (in mm)
C	0.650
G	1.300
X	0.420
Y	0.600
Y1	2.500

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